

<b>Notic of References Cited</b>	Application/Contr. No. 09/980,873		Applicant(s)/Patent Under Reexamination FUKUNAKA, TOSHIAKI	
	Examiner Scott R. Wilson		Art Unit 2826	Page 1 of 1

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	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	U	IBM Technical Disclosure Bulletin, November 1972. Vol. 15, Issue 6, pages 1977-1980 "Packaging of Integrated Circuits"
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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